

LTM4622 25LD LGA 6.25mm X 6.25mm X 1.82mm (TABLE OF MATERIAL DECLARATION)

This Package is RoHS compliant per EU RoHS Directive 2003/95/EC.
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+) polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.0360	Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1 1156-51-0/9003-36-5/21645-51-2 *non-disclosure	0.00675	18.76
				Continuous Filament Fiber Glass	65997-17-3	0.00598	16.63
				Copper Metal	7440-50-8	0.01857	51.62
				Zinc	7440-66-6	0.00001	0.02
				Chromium(III) oxide	1308-38-9	0.00000	0.01
				Epoxy Resin	*non-disclosure	0.00002	0.06
				Barium Compounds	7727-43-7	0.00120	3.33
				Silica amorphous	7631-86-9	0.00004	0.12
				Calcium caobonate	471-34-1	0.00000	0.01
				Amine compounds	*non-disclosure	0.00002	0.05
				Leveling agent and others	*non-disclosure	0.00005	0.15
				Acrylic Resin	*non-disclosure	0.00228	6.35
				Copper Compounds	147-14-8	0.00001	0.03
				Talc;not containing fibers like asbestos	14807-96-6	0.00014	0.38
				Aromatic carbonyl compounds	non-disclosure	0.00013	0.36
				Cyanoguanidine	461-58-5	0.00000	0.01
				Nickel	7440-02-0	0.00066	1.85
				Phosphorus	non-disclosure	0.00005	0.14
				Gold metal or alloy	7440-57-5	0.00003	0.09
				Palladium	7440-05-3	0.00001	0.03
**Ecotoxic substances	7440-38-2 7439-92-1	0.00000	0.01				
2	Solder Paste	Alloy	0.0086	Tin (Sn)	7440-31-5	0.00813	95.00
				Antimony (Sb)	7440-36-0	0.00043	5.00
3	Components	Passive/Active	0.0688	Iron Powder (Fe)	7439-89-6	0.04796	69.76
				Copper (Cu)	7440-50-8	0.01419	20.63
				Nickel (Ni)	7440-02-0	0.00079	1.14
				Tin (Sn)	7440-31-5	0.00058	0.85
				Ceramic (Ba) Compounds	12047-27-7	0.00523	7.61
4	Active Ics	Silicon	0.0015	Silicon (Si)	7440-21-3	0.00149	100.00
5	Wire	Gold	0.0006	Gold (Au)	7440-57-5	0.00055	99.99
7	Encapsulation	Epoxy Resin	0.0901	Fused Silica	60676-86-0	0.06958	77.20
				Epoxy Resin	non-disclosure	0.00802	8.90
				Phenol Resin	non-disclosure	0.00802	8.90
				Crytalline Silica	14808-60-7	0.00270	3.00
				Carbon Black	1333-86-4	0.00045	0.50
				Metal Hydroxide	non-disclosure	0.00135	1.50
Total Package Weight			0.2055				

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts